Special Issue

Ultrasonic and Electromagnetic Waves for Nondestructive Testing

Message from the Guest Editors

This Special Issue welcomes theoretical and practical contributions aimed at further understanding ultrasonic and electromagnetic nondestructive testing technologies, including (but not limited to) high-resolution detection, multidimensional imaging, image processing, and data fusion. In addition, it also seeks reports on quality assessment in specific application scenarios with ultrasonic and electromagnetic nondestructive testing technologies.

- ultrasonic testing
- microwave detection
- terahertz imaging
- infrared testing
- defect detection and evaluation
- in-situ detection
- intelligent recognition

We look forward to receiving your contributions.

Guest Editors

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Message from the Editor-in-Chief

Electronics is a multidisciplinary journal designed to appeal to a diverse audience of research scientists, practitioners, and developers in academia and industry. The journal is devoted to fast publication of latest technological breakthroughs, cutting-edge developments, and timely reviews of current and emerging technologies related to the broad field of electronics. Experimental and theoretical results are published as regular peer-reviewed articles or as articles within Special Issues guest-edited by leading experts in selected topics of interest.

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